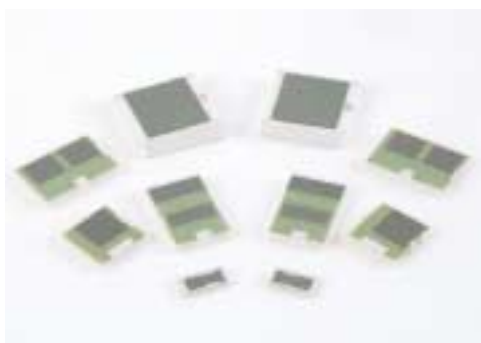


Surface Mount Terminations

50 Ω



General Specifications

Resistive Element:	Thick film
Substrate:	Alumina ceramic
Terminals:	Thick film silver
Resistance Value:	50 ohm, $\pm 2\%$

Notes: Tolerance is ± 0.10 , unless otherwise specified. Operating temperature is -55°C to $+125^{\circ}\text{C}$ (see chart). Designed to meet or exceed applicable portions of MIL-E-5400. All dimensions are in inches.

Specifications subject to change without notice.

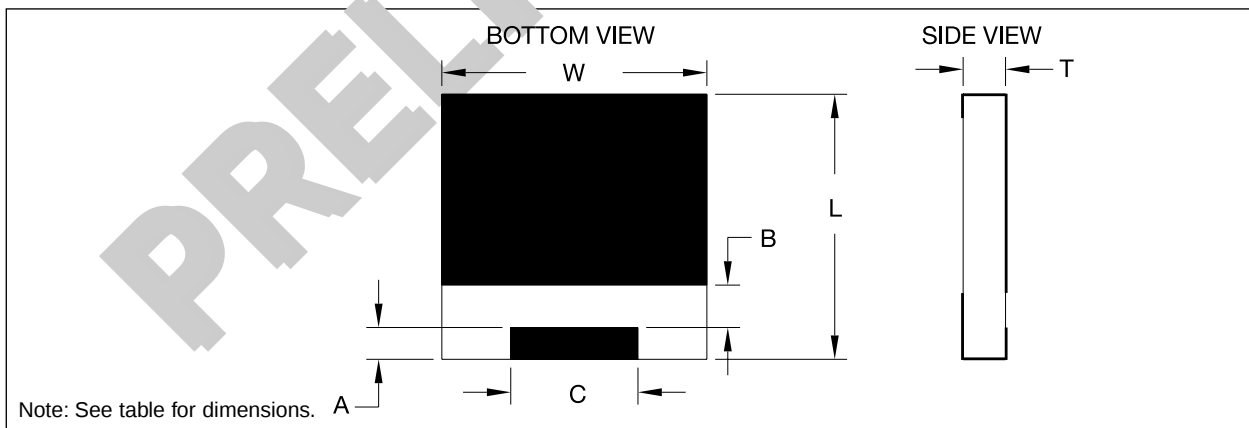
Features

- DC - 4.0 GHz
- 8-18 Watts
- Low Cost
- Alumina Ceramic
- Non-Nichrome Resistive Element
- 100% Tested

Dimensions

PART NUMBER	WIDTH	LENGTH	THK.	A	B	C
RFP-060120A15Z50	0.060	0.120	0.015	0.020	0.030	0.055
RFP-100200A25Z50	0.100	0.200	0.025	0.020	0.035	0.100
RFP-250250A4Z50	0.250	0.250	0.040	0.030	0.035	0.120
RFP-250375A4Z50	0.250	0.375	0.040	0.030	0.035	0.135
RFP-375250A4Z50	0.375	0.250	0.040	0.030	0.035	0.135
RFP-375375A4Z50	0.375	0.375	0.040	0.030	0.035	0.135

Outline Drawing



Available on Tape and Reel for Pick and Place Manufacturing.

Alumina Terminations

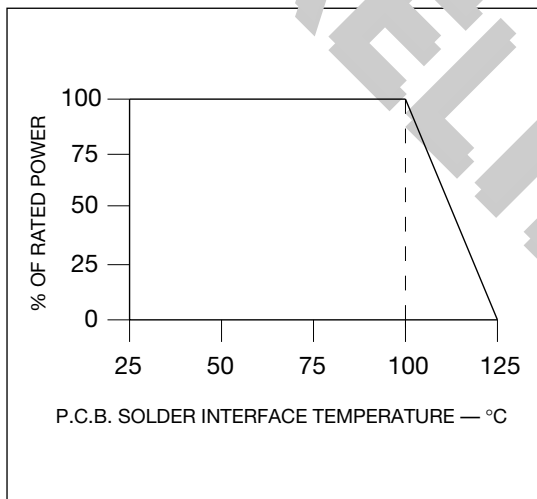
Anaren

RF Power

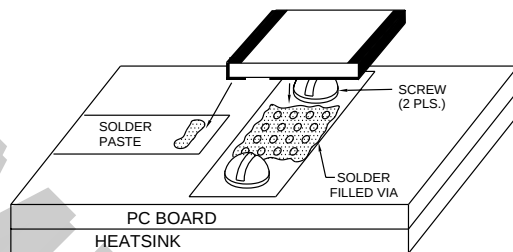
Typical Performance

PART NUMBER	VALUE (OHM)	POWER (WATTS)	MAX VSWR	FREQ. (GHz)
RFP-060120A15Z50	50	8	1.25:1	4.0
RFP-100200A25Z50	50	10	1.25:1	3.0
RFP-250250A4Z50	50	12	1.25:1	3.0
RFP-250375A4Z50	50	15	1.25:1	3.0
RFP-375250A4Z50	50	15	1.25:1	2.5
RFP-375375A4Z50	50	18	1.25:1	2.5

Power Derating



Suggested Mounting Procedures



1. Make sure that the devices are mounted on flat surfaces (.001" under the device) to optimize the heat transfer.
2. Position device on mounting surface and solder in place using an indalloy type or an SN63 type solder.
3. Solder leads in place using an SN63 type solder with a controlled temperature iron (210°C).

Available on Tape and Reel for Pick and Place Manufacturing.

